

#### POM copolymer

Easy flowing Injection molding type for precision molded parts and thin-walled molded parts with high rigidity, hardness and toughness; good chemical resistance to solvents, fuel and strong alkalis as well as good hydrolysis resistance; high resistance to thermal and oxidative degradation. With a high amount of carbon black . Ranges of applications: automotive engineering, especially out door applications

Product information			
Resin Identification Part Marking Code	POM >POM<		ISO 1043 ISO 11469
Rheological properties			
Melt volume-flow rate Temperature Load Moulding shrinkage, parallel	190 2.16   2.0 °	kg %	ISO 1133 ISO 294-4, 2577
Moulding shrinkage, normal	1.8 °	%	ISO 294-4, 2577
Typical mechanical properties			
Tensile modulus Tensile stress at yield, 50mm/min Tensile strain at yield, 50mm/min Nominal strain at break Flexural modulus Tensile creep modulus, 1h Tensile creep modulus, 1000h Charpy impact strength, 23°C Charpy impact strength, -30°C Charpy notched impact strength, -30°C Charpy notched impact strength, -30°C Ball indentation hardness, H 358/30 Poisson's ratio [C]: Calculated	9 0 25 0 2800   2500   1300   200   200   6.5	MPa % MPa MPa MPa kJ/m <sup>2</sup> kJ/m <sup>2</sup> kJ/m <sup>2</sup>	ISO 527-1/-2 ISO 527-1/-2 ISO 527-1/-2 ISO 527-1/-2 ISO 178 ISO 899-1 ISO 899-1 ISO 179/1eU ISO 179/1eU ISO 179/1eA ISO 179/1eA ISO 2039-1
Thermal properties Melting temperature, 10 ° C/min Temperature of deflection under load, 1.8 MPa Coefficient of linear thermal expansion (CLTE), parallel Thermal conductivity of melt Specific heat capacity of melt	0.155		ISO 11357-1/-3 ISO 75-1/-2 ISO 11359-1/-2 ISO 22007-2 ISO 22007-4
Electrical properties Relative permittivity, 100Hz Relative permittivity, 1MHz Dissipation factor, 100Hz Dissipation factor, 1MHz Volume resistivity	4 4 20 50 1E12		IEC 62631-2-1 IEC 62631-2-1 IEC 62631-2-1 IEC 62631-2-1 IEC 62631-2-1

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# HOSTAFORM<sup>®</sup> C 13021 10/1570

### HOSTAFORM®

Surface resistivity Electric strength Comparative tracking index		Ohm kV/mm	IEC 62631-3-2 IEC 60243-1 IEC 60112
Physical/Other properties			
Humidity absorption, 2mm	0.2	%	Sim. to ISO 62
Water absorption, 2mm	0.65		Sim. to ISO 62
Density		kg/m <sup>3</sup>	ISO 1183
Injection			
Drying Recommended	no		
Drying Temperature	100	°C	
Drying Time, Dehumidified Dryer	3 - 4	h	
Processing Moisture Content	≤0.2	%	
Melt Temperature Optimum	200	°C	
Min. melt temperature	190	°C	
Max. melt temperature	210	°C	
Screw tangential speed	≤0.3	m/s	
Mold Temperature Optimum	100	°C	
Min. mould temperature	80	°C	
Max. mould temperature	120	°C	
Hold pressure range	60 - 120	MPa	
Back pressure	4	MPa	
Ejection temperature	140	°C	
Characteristics			

#### Characteristics

Processing	Injection Moulding
Delivery form	Pellets
Additives	Release agent
Special characteristics	U.V. stabilised or stable to weather

### Additional information

Processing Notes

### **Pre-Drying**

Drying is not normally required. If material has come in contact with moisture through improper storage or handling or through regrind use, drying may be necessary to prevent splay and odor problems.

#### Storage

The product can then be stored in standard conditions until processed.

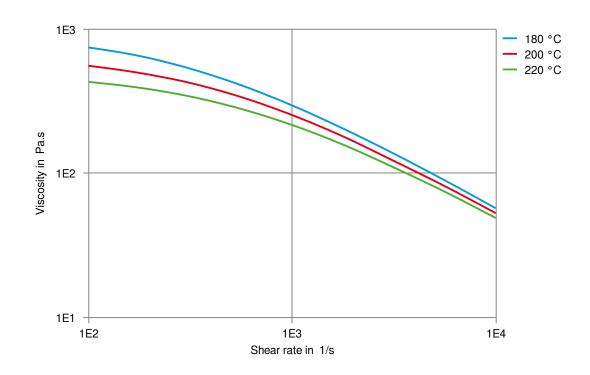




#### Automotive

OEM Bosch STANDARD N28 BN22-O027

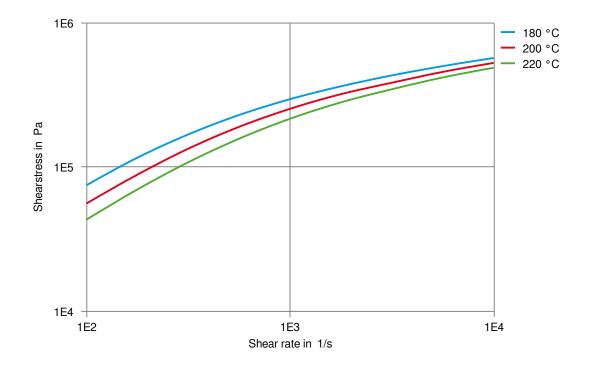
#### Viscosity-shear rate







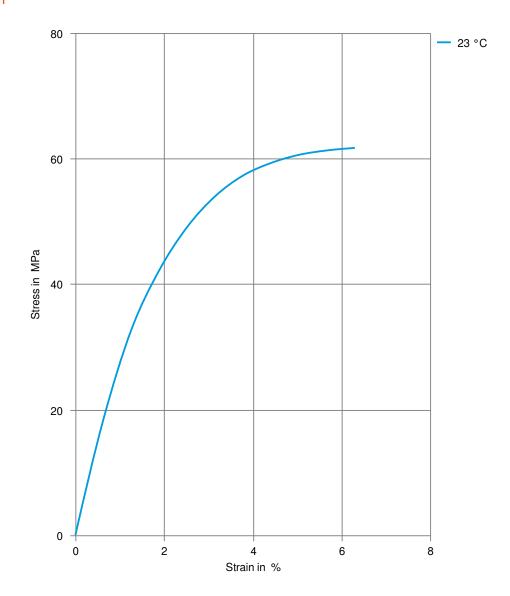
Shearstress-shear rate







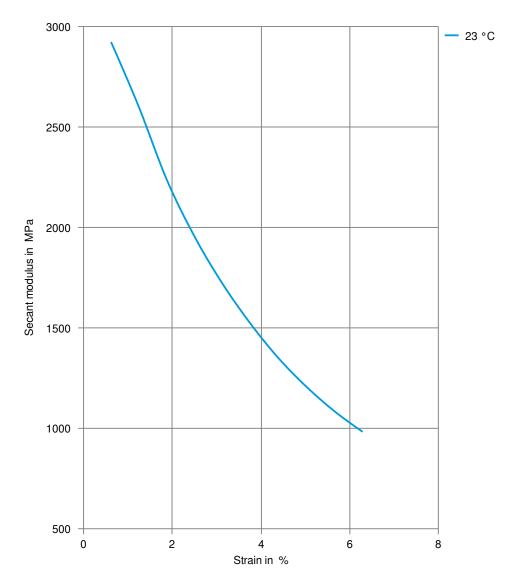
Stress-strain







#### Secant modulus-strain



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